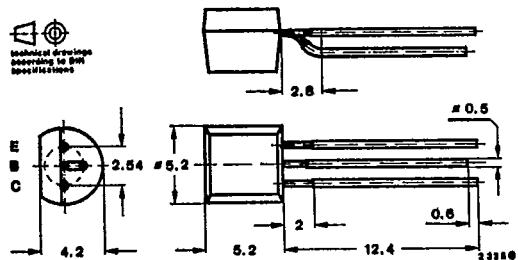


Silicon NPN Epitaxial Planar RF Transistor

Applications: General up to 100 MHz in common base configuration

Features:

- Small feedback capacitance

Dimensions in mm

Case
 10 A 3 DIN 41868
 JEDEC TO 92 Z
 Weight max. 0.2 g

Absolute maximum ratings

Collector-base voltage	V_{CBO}	30	V
Collector-emitter voltage	V_{CEO}	30	V
Emitter-base voltage	V_{EBO}	4	V
Collector current	I_C	25	mA
Base current	I_B	3	mA
Total power dissipation $T_{amb} \leq 45^\circ\text{C}$	P_{tot}	300	mW
Junction temperature	T_J	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55 ... +150	$^\circ\text{C}$

Thermal resistances

		Min.	Typ.	Max.
Junction ambient	R_{thJA}		350	K/W

T1.2/532.0484 E1

T-31-17

DC characteristics $T_{amb} = 25^\circ C$, unless otherwise specified

Collector cut-off current

 $V_{CB} = 20 V$
 $V_{CB} = 20 V, T_{amb} = 100^\circ C$

	I_{CBO}	Min.	Typ.	Max.
			60	nA
			10	μA

Collector-base breakdown voltage

 $I_C = 10 \mu A$

	$V_{(BR)CBO}$	30	v

Collector-emitter breakdown voltage

 $I_C = 2 mA$

	$V_{(BR)CEO}^{1)}$	30	v

Emitter-base breakdown voltage

 $I_E = 10 \mu A$

	$V_{(BR)EBO}$	4	v

DC forward current transfer ratio

 $V_{CE} = 10 V, I_C = 4 mA$

	h_{FE}	29	

AC characteristics $T_{amb} = 25^\circ C$

Gain bandwidth product

 $V_{CB} = 10 V, I_C = 1 mA, f = 100 MHz$

	f_T	580	MHz

Feedback capacitance

 $V_{CB} = 10 V, f = 0.47 MHz$

	C_{ob}	0.13	pF

Short circuit forward transfer admittance

 $V_{CB} = 10 V, I_C = 4 mA, f = 36 MHz$

	y_{fb}	80	mS

Collector current for: $|y_{fb}|$ max. $V_{CB} = 10 V, I_C = 4 mA, f = 36 MHz$

	I_C	10	mA

Short circuit output admittance

 $V_{CB} = 10 V, I_C = 4 mA, f = 36 MHz$

	g_{ob}	55	μS
	C_{ob}	1.6	pF

¹⁾ $\frac{t_p}{T} = 0.01, t_p = 0.3 ms$

7. Taping and Reeling

T-91-20

7.1. Taping of TO-92 Transistors

Standard reeling: Taped on reel, reeled together with a paper film.

7.1.1. Order Numbers

Add the taping-code to the order number.

Example:

Order-No. of Type	BC 238 C	DU	06	Z
Code for TO-92 Transistors				
Orientation of transistor on tape ¹⁾				
Additional marking for specials ²⁾				

¹⁾ 06 = View on flat side of transistor, view on gummed tape

05 = View on round side of transistor, view on gummed tape

²⁾ Additional marking "0": taping without paper film

Additional marking "Z": Zigzag folded tape in special box. Marking for orientation of transistor not necessary, because box can be opened on top or bottom

Example for order No.: BC 237 C DU Z

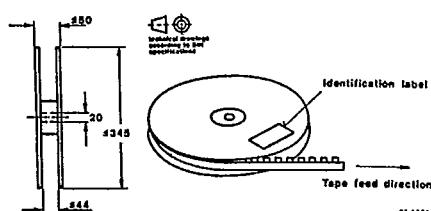


Fig. 7.1. Dimensions of reel in mm

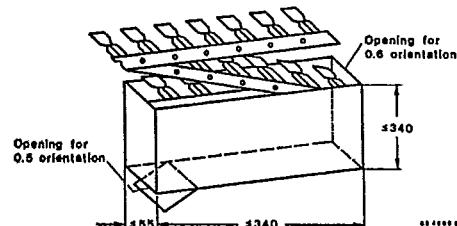


Fig. 7.2. Dimension of box for Zigzag folding in mm

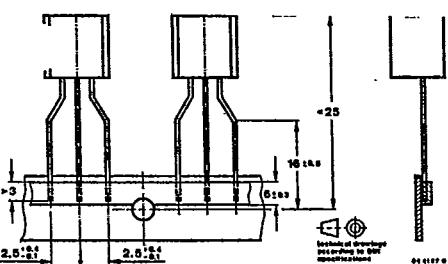


Fig. 7.3 Dimensions of tape in mm

7.1.2. Quantity of devices

1000 devices per reel

2000 devices per folded tape in special box.

7.2. Taped transistors in SOT 23 and SOT 143 case

7.2.1. Designation

a) Standard taping

Designation is attached with code GS 08 in case of standard taping. Example for normal version transistors as standard taped: BF 569-GS 08.

Example for R-version transistors as standard taped: BF 569 R-GS 08.

In case of standard taping, the transistor orientation on the tape is shown in Fig. 7.4 and Fig. 7.5.

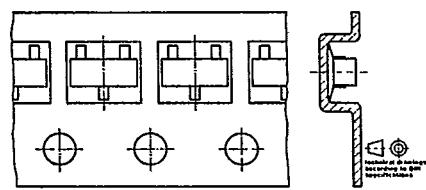


Fig. 7.4 Standard taped SOT 23

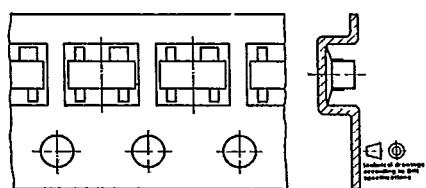


Fig. 7.5. Standard taped SOT 143

T-91-20

b) Reverse taping

Designation is attached with code GS 07 in case of reverse taping. Example for normal version transistors as reverse taped: BF 569-GS 07.

Example for R-version transistors as reverse taping: BF 569 R-GS 07.

In case of reverse taping, the transistor orientation on the tape is shown in Fig. 7.6.

Regarding MOS-FET and MES-FET devices, reverse taping is at present not available.

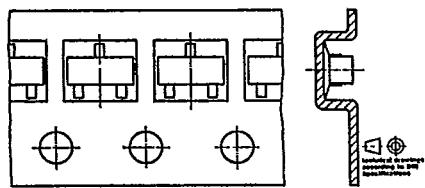


Fig. 7.6 Reverse taped SOT 23

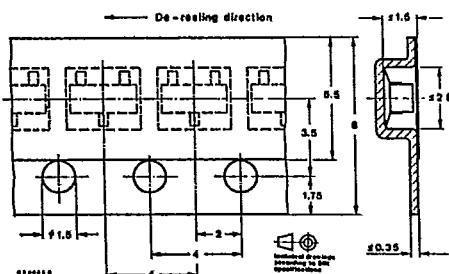


Fig. 7.7 Dimensions of tape in mm

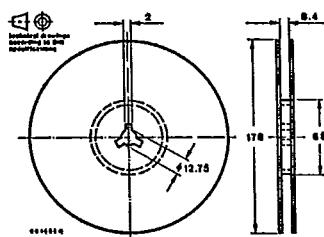


Fig. 7.8 Dimensions of reel in mm

7.2.2 Quantity of devices

3000 devices per reel